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SALKOVIC et al.(10) **Pub. No.: US 2022/0377897 A1**(43) **Pub. Date: Nov. 24, 2022**(54) **MAGNETIC INLAY WITH ELECTRICALLY
CONDUCTIVE VERTICAL THROUGH
CONNECTIONS FOR A COMPONENT
CARRIER****Publication Classification**(51) **Int. Cl.****H05K 1/16** (2006.01)**H01F 27/28** (2006.01)**H01F 41/04** (2006.01)(52) **U.S. Cl.**CPC **H05K 1/165** (2013.01); **H01F 27/2804**(2013.01); **H01F 41/041** (2013.01); **H01F****2027/2814** (2013.01); **H01F 2027/2809**(2013.01); **H05K 2201/09609** (2013.01); **H05K****2201/09627** (2013.01); **H05K 2201/09063**(2013.01); **H05K 2201/086** (2013.01)(71) Applicant: **AT&S Austria Technologie &
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ABSTRACT

A magnetic inlay includes a magnetic matrix and a plurality of electrically conductive vertical through connections extending vertically through the magnetic matrix. Further, a component carrier including the magnetic inlay and a method of manufacturing said magnetic inlay are described.

